

## Claim Amendments

Claims 1-11 (cancelled).

12. (new) A method of electroless plating of features on a semiconductor wafer, comprising the steps of:

supporting said wafer with a plurality of rollers;  
rotating said wafer by rotating each of said plurality of rollers; and  
flowing plating solution over the surface of said wafer.

13. (new) The method of Claim 12, wherein said step of supporting comprises supporting said wafer in a groove in each of said rollers in said plurality.

14. (new) The method of Claim 12, wherein said step of rotating said wafer comprises turning a gear on each of said rollers by turning a central sun gear engaged with said gear on each of said rollers.

15. (new) The method of Claim 12, further comprising the step of immersing said wafer and said rollers in said plating solution.

16. (new) The method of Claim 15, wherein said step of immersing said wafer comprises immersing said wafer and said rollers in a tank and said step of flowing plating solution comprises flowing said solution from the bottom of said tank to the top of said tank.

17. (new) The method of Claim 12, wherein said step of supporting said wafer comprises swinging one of said plurality of rollers out of position, loading said wafer on the remaining rollers in said plurality, and then swinging said roller back into position.

18. (new) A method of electroless plating of features on a semiconductor wafer, comprising the steps of:

supporting said wafer with a plurality of rollers, each of said rollers having grooves for supporting an edge of said wafer;

immersing said wafer in plating solution;

rotating said wafer by rotating said rollers; and

flowing plating solution over the surface of said wafer during said step of rotating said wafer.

19. (new) The method of Claim 18, wherein said step of rotating said wafer comprises turning a gear on each of said rollers by turning a central sun gear engaged with said gear on each of said rollers.

20. (new) The method of Claim 18, wherein said step of immersing said wafer comprises immersing said wafer and said rollers in a tank and said step of flowing plating solution comprises flowing said solution from the bottom of said tank to the top of said tank.

21. (new) The method of Claim 18, wherein said step of supporting said wafer comprises swinging one of said plurality of rollers out of position, loading said wafer on the remaining rollers in said plurality, and then swinging said roller back into position.